

WHAT IS CLAIMED IS:

1. A semiconductor device having a multiple layered ridge, said ridge including:

a first semiconductor layer forming the bottom part of said ridge, said first semiconductor layer having a  
5 first etching speed in a first etchant;

a second semiconductor layer disposed above said first semiconductor layer, said second semiconductor layer having a second etching speed in the first etchant;  
and

10 a third semiconductor layer disposed above said second semiconductor layer and forming the top part of said ridge, said third semiconductor layer having a third etching speed in the first etchant,

wherein the second etching speed is higher than the  
15 first etching speed and slower than the third etching speed.

2. The semiconductor device according to claim 1, wherein said second semiconductor layer has a bottom surface located near the first semiconductor layer and top surface located near the third semiconductor layer,  
5 and wherein the second etching speed is variable and increases monotonically from the layer's bottom surface to the layer's top surface.

3. The semiconductor device according to claim 2, wherein the second etching speed increases continuously from the bottom surface of said second semiconductor layer to the top surface of said second semiconductor  
5 layer.

4. The semiconductor device according to claim 1,  
wherein said second semiconductor layer has a bottom  
surface located near the first semiconductor layer and  
top surface located near the third semiconductor layer,  
5 and wherein the second etching speed is variable and it  
increases in one or more steps from the layer's bottom  
surface to the layer's top surface.

5. The semiconductor device according to claim 2,  
wherein the second semiconductor layer comprises two or  
more atomic elements, and wherein the stoichiometric  
ratio of the atomic elements of said second semiconductor  
5 layer is changed to thereby make the second etching speed  
variable.

6. The semiconductor device according to claim 1,  
wherein said first semiconductor layer comprises a  
composition of  $\text{Al}_{x_1}\text{Ga}_{1-x_1}\text{As}$  where the stoichiometric  
parameter  $x_1$  is substantially constant, wherein said  
5 third semiconductor layer comprises a composition of  
 $\text{GaAs}$ , and wherein said second semiconductor layer  
comprises a composition of  $\text{Al}_{x_2}\text{Ga}_{1-x_2}\text{As}$  where the  
stoichiometric parameter  $x_2$  is a variable.

7. The semiconductor device according to claim 6,  
wherein the stoichiometric parameter  $x_1$  for the first  
semiconductor layer is in a range of 0.2 to 0.5.

8. The semiconductor device according to claim 1  
further comprising an electrode layer disposed above said  
third semiconductor layer and covering at least a side of  
said ridge portion in the longitudinal direction, wherein

5 the thickness of said electrode layer is equal to or more than 100 nm.

9. The semiconductor device according to claim 1 wherein said second semiconductor layer has a thickness in a range of 5 nm to 1000 nm.

10. The semiconductor device according to claim 1 wherein said second semiconductor layer has a thickness in a range of 25 nm to 100 nm.

11. The semiconductor device according to claim 1 wherein said second semiconductor layer has a thickness in a range of 25 nm to 35 nm.

12. The semiconductor device according to claim 11 wherein the thickness of said first semiconductor layer is greater than the thickness of said second semiconductor layer, and wherein the thickness of the  
5 third semiconductor layer is greater than the thickness of the second semiconductor layer.

~~13.~~ A method of manufacturing a semiconductor device having a multiple layered ridge, the method comprising the steps of:

forming a first semiconductor layer as a bottom  
5 part of the ridge, said first semiconductor layer being etched at a first etching speed by a first etchant;

forming a second semiconductor layer above said first semiconductor layer, said second semiconductor layer being etched at a second etching speed by the first  
10 etchant; and

forming a third semiconductor layer above said second semiconductor layer as a top part of the ridge, said third semiconductor layer being etched at a third etching speed by the first etchant,

15 wherein the second etching speed is higher than the first etching speed and slower than the third etching speed.

14. The method according to claim 13, wherein said second semiconductor layer has a bottom surface located near said first semiconductor layer and top surface located near said third semiconductor layer, and wherein  
5 said second semiconductor layer is formed with a composition that causes the second etching speed to be variable and to increase monotonically from the layer's bottom surface to the layer's top surface.

15. The semiconductor device according to claim 14, wherein the second etching speed increases continuously from the bottom surface of said second semiconductor layer to the top surface of said second semiconductor  
5 layer.

16. The method according to claim 13, wherein said second semiconductor layer has a bottom surface located near said first semiconductor layer and top surface located near said third semiconductor layer, and wherein  
5 said second semiconductor layer is formed with a composition that causes the second etching speed to be variable and to increase in one or more steps from the layer's bottom surface to the layer's top surface.



side of said ridge portion in the longitudinal direction,  
5 wherein the thickness of said electrode layer is equal to  
or more than 200 nm.

22. A semiconductor device having a multiple  
layered ridge formed at a first surface of a substrate,  
said ridge including:

a base attached to the substrate, an upper face  
5 located above the base, and at least a first side face  
located between the ridge's upper face and the base;

a first semiconductor layer located closer to the  
base than the upper face of the ridge, said first  
semiconductor layer having a composition of  $\text{Al}_{x1}\text{Ga}_{1-x1}\text{As}$   
10 where the stoichiometric parameter  $x1$  is substantially  
constant;

a second semiconductor layer located above said  
first semiconductor layer and below said upper face, said  
second semiconductor layer having a composition of  
15  $\text{Al}_{x2}\text{Ga}_{1-x2}\text{As}$  where the stoichiometric parameter  $x2$  is  
variable with a range of values which are less than or  
equal to  $x1$ ; and

a third semiconductor layer located above said  
second semiconductor layer and below said upper face,  
20 said third semiconductor layer having a composition of  
 $\text{Al}_{x3}\text{Ga}_{1-x3}\text{As}$  where the stoichiometric parameter  $x3$  is  
substantially constant and substantially less than or  
equal to the lowest value of the stoichiometric parameter  
 $x2$ ; and

25 wherein said second semiconductor layer has a  
bottom surface located near the first semiconductor layer  
and top surface located near the third semiconductor  
layer,

wherein the stoichiometric parameter X2 decreases  
30 monotonically from the bottom surface of the second  
semiconductor layer to the top surface of the second  
semiconductor layer, and

wherein said first side face comprises a forward  
mesa surface.

23. The semiconductor device according to claim 22,  
wherein said second semiconductor layer has a bottom  
surface located near the first semiconductor layer and  
top surface located near the third semiconductor layer,  
5 and wherein the stoichiometric parameter x2 decreases  
monotonically from the layer's bottom surface to the  
layer's top surface.

24. The semiconductor device according to claim 23,  
wherein the stoichiometric parameter x2 decreases  
continuously from the bottom surface of said second  
semiconductor layer to the top surface of said second  
5 semiconductor layer.

25. The semiconductor device according to claim 22,  
wherein said second semiconductor layer has a bottom  
surface located near the first semiconductor layer and  
top surface located near the third semiconductor layer,  
5 and wherein the stoichiometric parameter x2 decreases in  
one or more steps from the layer's bottom surface to the  
layer's top surface.

26. The semiconductor device according to claim 22,  
wherein said first side face comprises a concave surface.

27. The semiconductor device according to claim 22, wherein the stoichiometric parameter  $x_1$  for the first semiconductor layer is in a range of 0.2 to 0.5.

28. The semiconductor device according to claim 22, wherein the stoichiometric parameter  $x_1$  for the first semiconductor layer is in a range of 0.25 to 0.35.

29. The semiconductor device according to claim 22, wherein the stoichiometric parameter  $x_1$  for the first semiconductor layer is in a range of 0.2 to 0.5, and wherein the stoichiometric parameter  $x_3$  for the third  
5 semiconductor layer is less than or equal to 0.05.

30. The semiconductor device according to claim 22, wherein the third semiconductor layer comprises GaAs with the stoichiometric parameter  $x_3$  being substantially equal to zero.

31. The semiconductor device according to claim 22 wherein said second semiconductor layer has a thickness in a range of 5 nm to 1000 nm.

32. The semiconductor device according to claim 22 wherein said second semiconductor layer has a thickness in a range of 25 nm to 100 nm.

33. The semiconductor device according to claim 22 wherein said second semiconductor layer has a thickness in a range of 25 nm to 35 nm.



34. The semiconductor device according to claim 32 wherein the thickness of said first semiconductor layer is greater than the thickness of said second semiconductor layer, and wherein the thickness of the  
5 third semiconductor layer is greater than the thickness of the second semiconductor layer.

35. The semiconductor device according to claim 22 further comprising an electrode layer disposed above said third semiconductor layer and covering at least the side of said ridge portion in the longitudinal direction,  
5 wherein the thickness of said electrode layer is equal to or more than 100 nm.

36. The semiconductor device according to claim 22 further comprising an electrode layer disposed above said third semiconductor layer and covering at least the side of said ridge portion in the longitudinal direction,  
5 wherein the thickness of said electrode layer is equal to or more than 150 nm.

37. The semiconductor device according to claim 22 further comprising an electrode layer disposed above said third semiconductor layer and covering at least the side of said ridge portion in the longitudinal direction,  
5 wherein the thickness of said electrode layer is equal to or more than 200 nm.

38. A method of manufacturing a semiconductor device having a multiple layered ridge, the ridge having a base attached to a substrate, an upper face located above the base, and at least a first side face located  
5 between the ridge's upper face and the base, the method comprising the steps of:

(a) forming a first semiconductor layer located closer to the base than the upper face of the ridge, the first semiconductor layer having a composition of  
10  $\text{Al}_{x_1}\text{Ga}_{1-x_1}\text{As}$  where the stoichiometric parameter  $x_1$  is substantially constant;

(b) forming a second semiconductor layer over the first semiconductor layer and located below the upper face, the second semiconductor layer having a bottom  
15 surface adjacent to the first semiconductor layer and top surface opposite to the bottom surface, the second semiconductor layer having a composition of  $\text{Al}_{x_2}\text{Ga}_{1-x_2}\text{As}$  where the stoichiometric parameter  $x_2$  is variable with a range of values which are less than or equal to  $x_1$ , the  
20 second layer being formed such that the stoichiometric parameter  $x_2$  decreases substantially monotonically from the bottom surface of the second semiconductor layer to the top surface of the second semiconductor layer; and

(c) forming a third semiconductor layer over the  
25 second semiconductor layer and located below the upper face, the third semiconductor layer having a composition of  $\text{Al}_{x_3}\text{Ga}_{1-x_3}\text{As}$  where the stoichiometric parameter  $x_3$  is substantially constant and substantially less than or equal to the lowest value of the stoichiometric parameter  
30  $x_2$ ; and

(d) exposing selected portions of the first, second, and third semiconductor layers to a common

etchant to form the ridge such that at least a portion of  
the first side surface of the ridge has a slope of a  
35 forward mesa ridge.

39. The method of claim 38, wherein the second  
semiconductor layer is formed such that the  
stoichiometric parameter  $x_2$  decreases continuously from  
the bottom surface of said second semiconductor layer to  
5 the top surface of said second semiconductor layer.

40. The method of claim 38, wherein the second  
semiconductor layer is formed such that the  
stoichiometric parameter  $x_2$  decreases in one or more  
steps from the bottom surface of said second  
5 semiconductor layer to the top surface of said second  
semiconductor layer.

41. The method of claim 38, wherein the first side  
face comprises a concave surface.

42. The method of claim 38, wherein the  
stoichiometric parameter  $x_1$  for the first semiconductor  
layer is in a range of 0.2 to 0.5.

43. The method of claim 38, wherein the  
stoichiometric parameter  $x_1$  for the first semiconductor  
layer is in a range of 0.25 to 0.35.

44. The method of claim 38, wherein the  
stoichiometric parameter  $x_1$  for the first semiconductor  
layer is in a range of 0.2 to 0.5, and wherein the  
stoichiometric parameter  $x_3$  for the third semiconductor

5 layer is less than or equal to 0.05.

45. The method of claim 38, wherein said second semiconductor layer has a thickness in a range of 5 nm to 1000 nm.

46. The method of claim 38, wherein said second semiconductor layer has a thickness in a range of 25 nm to 100 nm.

47. The method of claim 38, wherein said second semiconductor layer has a thickness in a range of 25 nm to 35 nm.

48. The method of claim 46, wherein the thickness of said first semiconductor layer is greater than the thickness of said second semiconductor layer, and wherein the thickness of the third semiconductor layer is greater than the thickness of the second semiconductor layer.

49. The method according to claim 38, further comprising a step of forming an electrode layer above said third semiconductor layer and covering at least a portion of the first side of said ridge portion in the longitudinal direction, wherein the thickness of said electrode layer is equal to or more than 100 nm.